

10/066421

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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10066421	FILING DATE 01/30/2002	CLASS 257	SUBCLASS 784	GAU 2815
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EXAMINER
S. Clark

**APPLICANTS: Baldonado Herald; Mandapat Celine; Perez Paul;

**CONTINUING DATA VERIFIED:
THIS APPLN CLAIMS BENEFIT OF 60/343,652 12/28/2001

** FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed	<input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO	
35 USC 119 conditions met	<input type="checkbox"/> yes <input type="checkbox"/> no	TI-32857	
Verified and Acknowledged Examiners's initials			
TITLE : Method and system of wire bonding using interposer pads			

U.S. DEPT. OF COMM./PAT. & TM-PTO-435L(Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.	Print Fig.
TERMINAL DISCLAIMER		Primary Examiner		
		Application Examiner		
PREPARED FOR ISSUE				
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